

● General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

● Features

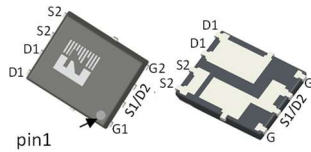
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Half-Bridge - N-channel
- AEC-Q101 qualified

● Application

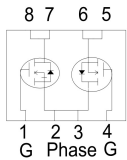
- BLDC motor driver
- DC-DC



● Product Summary



DFN5*6



$V_{DS}=40V$

$R_{DS(ON)}=4.1m\Omega$

$I_D=58A$



● Ordering Information

Part NO.	ZMDA68410N
Marking	ZMD68410
Packing information	REEL TAPE
Basic ordering unit (pcs)	3000

● Absolute Maximum Ratings ($T_A=25^\circ C$, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Drain-source voltage	V_{DS}		-	40	V
Gate-source voltage ^①	V_{GS}		-20	20	V
Continuous drain current	I_D	$V_{GS}=10V, T_C=25^\circ C$	-	58	A
	I_D	$V_{GS}=10V, T_C=75^\circ C$	-	48	A
	I_D	$V_{GS}=10V, T_C=100^\circ C$	-	41	A
Pulsed drain current ^①	I_{DM}	Pulsed; $t_p \leq 10 \mu s; T_C = 25^\circ C$;	-	240	A
Total power dissipation	P_D	$T_C=25^\circ C$	-	39	W
Total power dissipation	P_D	$T_A=25^\circ C$	-	3.3	W
Operating junction temperature	T_J		-55	175	$^\circ C$
Storage temperature	T_{STG}		-55	175	$^\circ C$
Single pulse avalanche energy	E_{AS}	$L=0.1mH, V_{GS}=10V, R_g=25\Omega$,	-	35	mJ
		$L=0.5mH, V_{GS}=10V, R_g=25\Omega$,	-	73.5	mJ
ESD level (HBM)			CLASS 2		

● Thermal Resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	3.8	°C/W
Thermal resistance, junction - ambient ^②	R_{thJA}	-	-	45	°C/W
Soldering temperature(total time<10s)	T_{sold}	-	-	260	°C

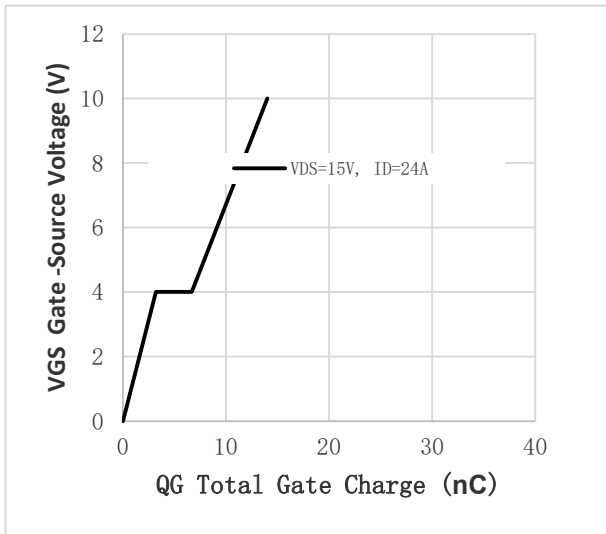
● Electronic Characteristics ($T_j=25^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2	2.7	3.2	V
Drain-source leakage current	I_{DSS}	$V_{GS}=0V, V_{DS}=40V$	-	-	1	μA
Gate- source leakage current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	100	nA
Static drain-source on resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=14A, T_j=25^{\circ}\text{C}$	-	4.1	5.5	m Ω
Forward transconductance	g_{FS}	$V_{DS}=5V, I_{SD}=10A$	-	7	-	S
Diode forward voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=14A$	-	-	1.3	V

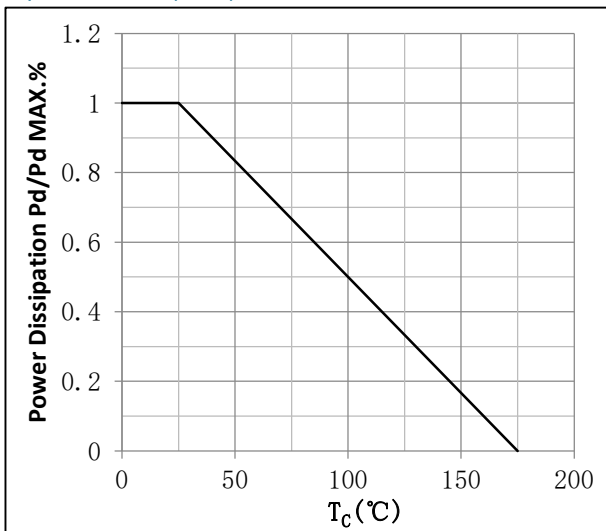
● Dynamic Characteristics ($T_j=25^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1\text{MHz}, V_{DS}=25V, V_{GS}=0V$	-	908	-	pF
Output capacitance	C_{oss}		-	244	-	pF
Reverse transfer capacitance	C_{rss}		-	10	-	pF
Gate resistance	R_g	$f=1\text{MHz}$	-	1.2	-	Ω
Total gate charge	Q_g	$V_{DD}=15V, I_D=20A, V_{GS}=10V$	-	14	-	nC
Gate-source charge	Q_{gs}		-	3.2	-	nC
Gate-drain charge	Q_{gd}		-	3.5	-	nC
Turn-on delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V, R_G=3.3\Omega, I_D=20A$	-	4.5	-	ns
Turn-on rise time	t_r		-	2	-	ns
Turn-off delay time	$t_{D(off)}$		-	8	-	ns
Turn-off fall time	t_f		-	4	-	ns
Reverse recovery time	t_{rr}	$V_{DD}=20V, di/dt=100A/\mu s, I_S=20A$	-	26	-	ns
Reverse recovery charge	Q_{rr}		-	12	-	nC

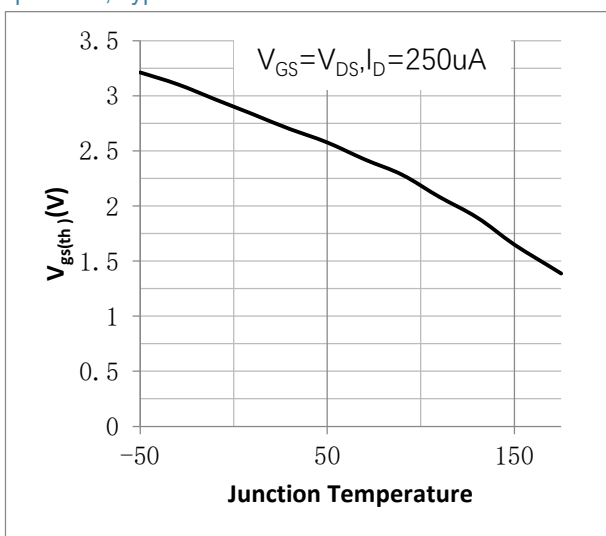
● Fig.1 Gate-source voltage as a function of gate charge; Typical values; $T_J=25^\circ\text{C}$



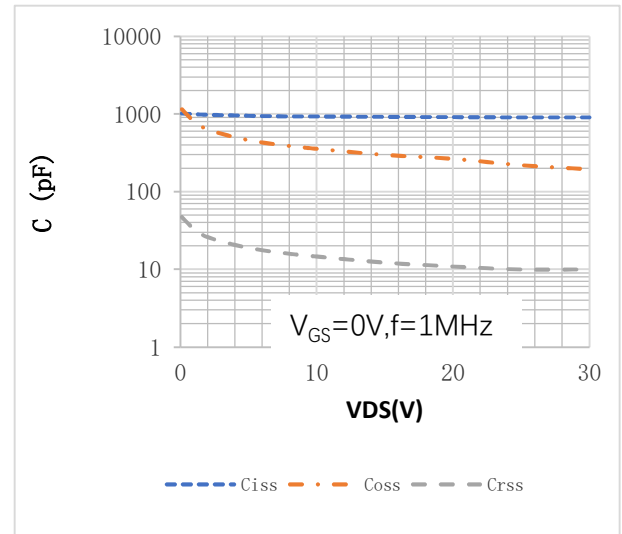
● Fig.3 Normalized total power dissipation as a function of case temperature; Calculative values Normalized Power Dissipation = $P_d/P_d(25^\circ\text{C})$



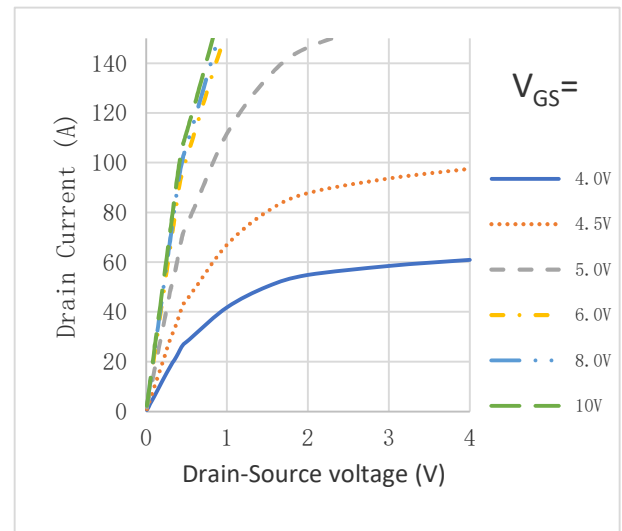
● Fig.5 Gate-source threshold voltage as a function of junction temperature; Typical values



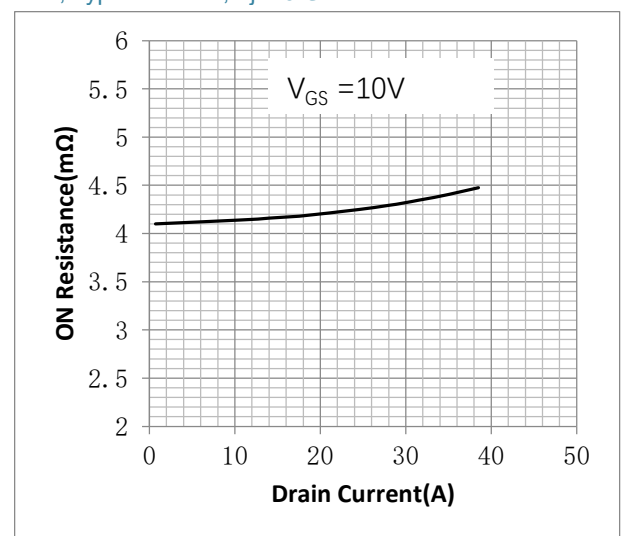
● Fig.2 Input, output and reverse transfer capacitances as a function of drain-source voltage; Typical values; $T_J=25^\circ\text{C}$



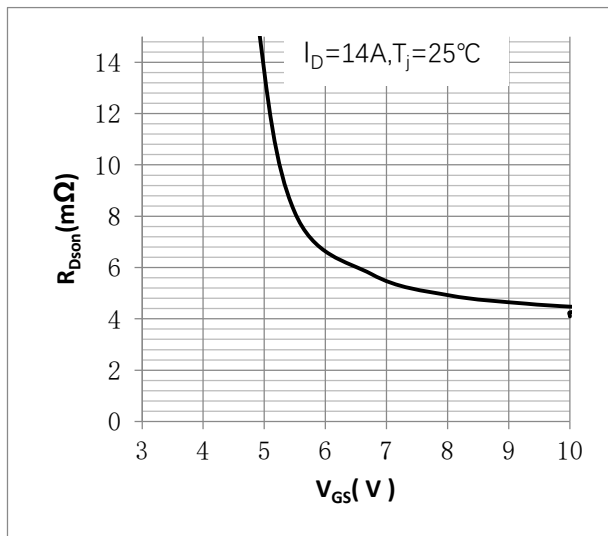
● Fig.4 Output characteristics: drain current as a function of drain-source voltage; Typical values; $T_J=25^\circ\text{C}$



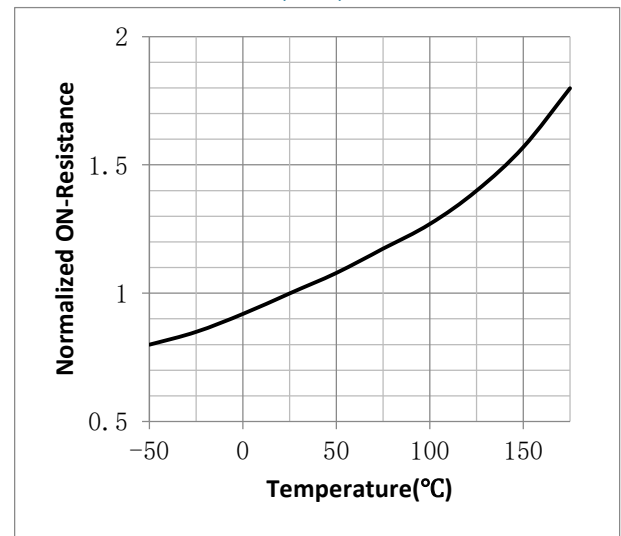
● Fig.6 Drain-source on-state resistance as a function of drain current; Typical values; $T_J=25^\circ\text{C}$



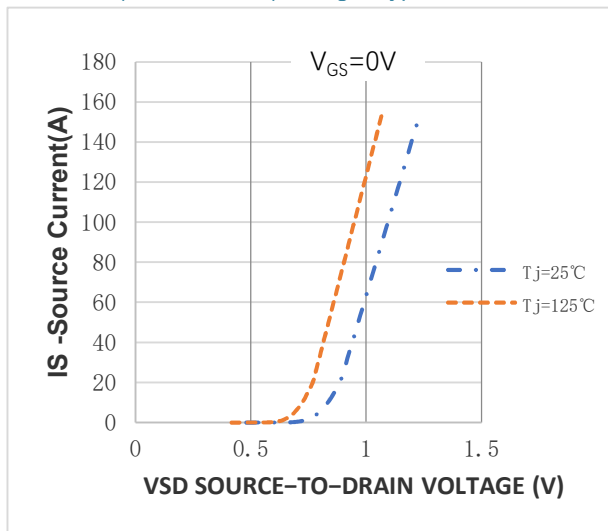
● Fig.7 Drain-source on-state resistance as a function of gate-source voltage; Typical values



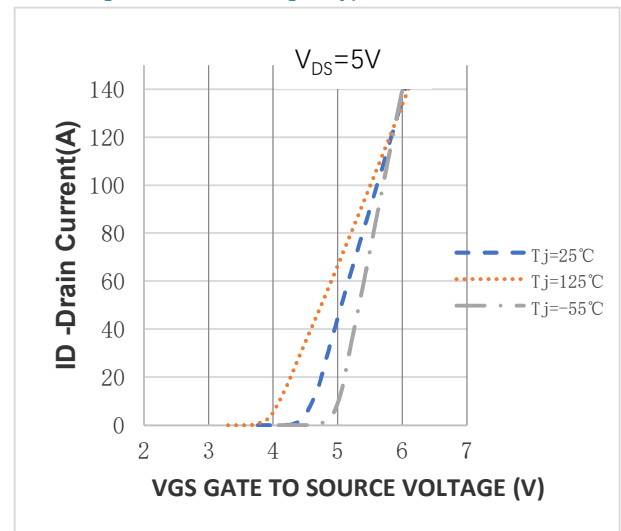
● Fig.8 Normalized drain-source on-state resistance factor as a function of junction temperature; Typical values Normalized On-Resistance= $R_{DS(on)}/R_{DS(on)}(25^\circ C)$



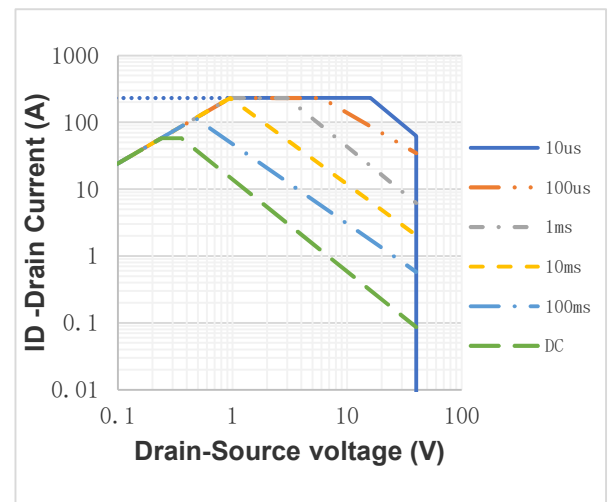
● Figure 9. Source (diode forward) current as a function of source-drain (diode forward) voltage; Typical values



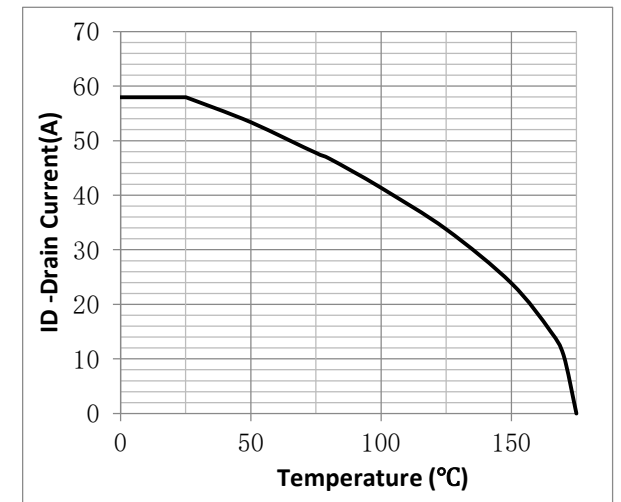
● Figure 10. Transfer characteristics: drain current as a function of gate-source voltage; Typical values



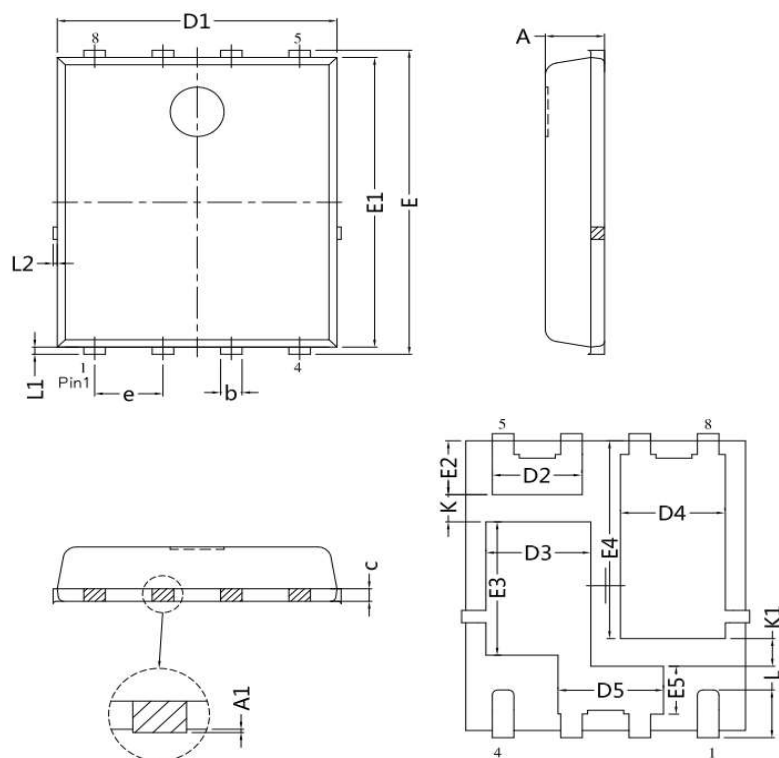
● Fig.11 Safe operating area: continuous and peak drain currents as a function of drain-source voltage; Calculative values



● Fig.12 Continuous drain current as a function of case temperature³; Calculative values



● Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	0	---	0.05
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D1	5.10	5.20	5.30
D2	1.52	1.67	1.82
D3	1.78	1.95	2.10
D4	1.78	1.95	2.10
D5	1.81	1.96	2.11
E	6.00	6.15	6.30
E1	5.76	5.86	5.96
E2	0.94	1.09	1.24
E3	2.55	2.70	2.85
E4	3.85	4.0	4.15
E5	0.82	0.97	1.12
e	1.27 BSC		
L	0.90	0.96	1.06
L1	0.05	0.15	0.25
L2	0.02	0.08	0.15
K	0.55	---	---
K1	0.56	---	---

Note:

1. Refer to JEDEC MO-240.

● Note

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=+20V/-10V$, $T_j=175^{\circ}C$, $t=1000$ hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=10V$.

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● Revision History

Version	Date	Change
A	2023/2/20	New
B	2023/4/12	Correct the symbol figure
C	2023/6/20	Remove Qg(4.5V)
D	2025/7/24	1. Apply new datasheet format. 2. Update RDSON,ID,SOA.